



Material Content Data Sheet



Sales Product Name		TLS205B0EJV		Issued		24. January 2018		
MA#		MA001137134						
Package		PG-DSO-8-52		Weight*		83.76 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.268	1.51	1.51	15139	15139
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		109	
	non noble metal	zinc	7440-66-6	0.036	0.04		434	
	non noble metal	iron	7439-89-6	0.728	0.87		8688	
wire	non noble metal	copper	7440-50-8	29.548	35.28	36.20	352760	361991
	non noble metal	copper	7440-50-8	0.067	0.08	0.08	801	801
	encapsulation	organic material	carbon black	1333-86-4	0.100	0.12		1199
encapsulation	plastics	epoxy resin	-	4.620	5.52		55163	
	inorganic material	silicondioxide	60676-86-0	45.502	54.33	59.97	543233	599595
leadfinish	non noble metal	tin	7440-31-5	0.695	0.83	0.83	8299	8299
plating	noble metal	silver	7440-22-4	0.725	0.86	0.86	8650	8650
glue	plastics	epoxy resin	-	0.116	0.14		1381	
	noble metal	silver	7440-22-4	0.347	0.41	0.55	4144	5525
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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